NOTICE OF APPEAL FROM THE PRIMARY EXAMINER TO Docket No. THE BOARD OF PATENT APPEALS AND INTERFERENCES (Large Entity) END920010002/US1 In Re Application Of: Ray et al. JAN 08200 Examiner Filing Date Group Art Unit Serial No. 09/772,812 2/8/01 Nguyen, Ha T. 2812 Invention: LEAD-FREE SOLDER STRUCTURE AND METHOD FOR HIGH FATIGUE LIFE TO THE COMMISSIONER FOR PATENTS: Applicant(s) hereby appeal(s) to the Board of Patent Appeals and Interferences from the decision of the Primary Examiner dated 9/9/2003 finally rejecting Claim(s) 1-10 and 12-36 The fee for this Notice of Appeal is: A check in the amount of the fee is enclosed. \boxtimes The Director has already been authorized to charge fees in this application to a Deposit Account. The Director is hereby authorized to charge any fees which may be required, or credit any overpayment to Deposit Account No. 09-0457(IBM) 01/\dagger\2004 TBESHAH1 00000003 090457 09779812

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Jack P. Fredom

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Dated: 1/6/2004

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Cold date: 01/09/2004 TBESHAH1

01/09/2004 AUONDAF1 0000064 090457 09772812 01 FC:1401 330.00 CR I certify that this document and fee is being deposited on 1/6/2004 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the

Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Signature of Person Mailing Correspondence

Kim Dwileski

Typed or Printed Name of Person Mailing Correspondence